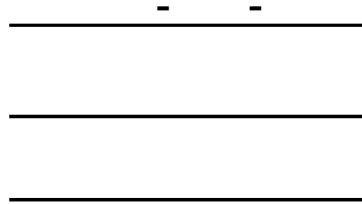




# ORIENT

## Photo coupler

### Product Data Sheet



#### 一级代理商：

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FAX：0755-27447020

[www.frxelec.com](http://www.frxelec.com)



### 1. Features

· ( ) . % , ,

· - ( ) . ( , )

· ( )

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### 2. Instructions

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- ,

### 3. Application Range

( ).

( ).

( ). ,

### 4. Max Absolute rated Value (Normal Temperature=25 )

	( )		
*			
		- +	
		- +	
*			

\* . , . . %

(1)

(2)

(3)

\* .



### 5. Opto-electronic Characteristics(Normal Temperature=25 )

Parameter	Symbol	Min	Typ.*	Max	Unit	Condition
Input		---	.	.		
		---		---		,
		---	---			, .
Output						

## 6. Rank table of current transfer ratio CTR

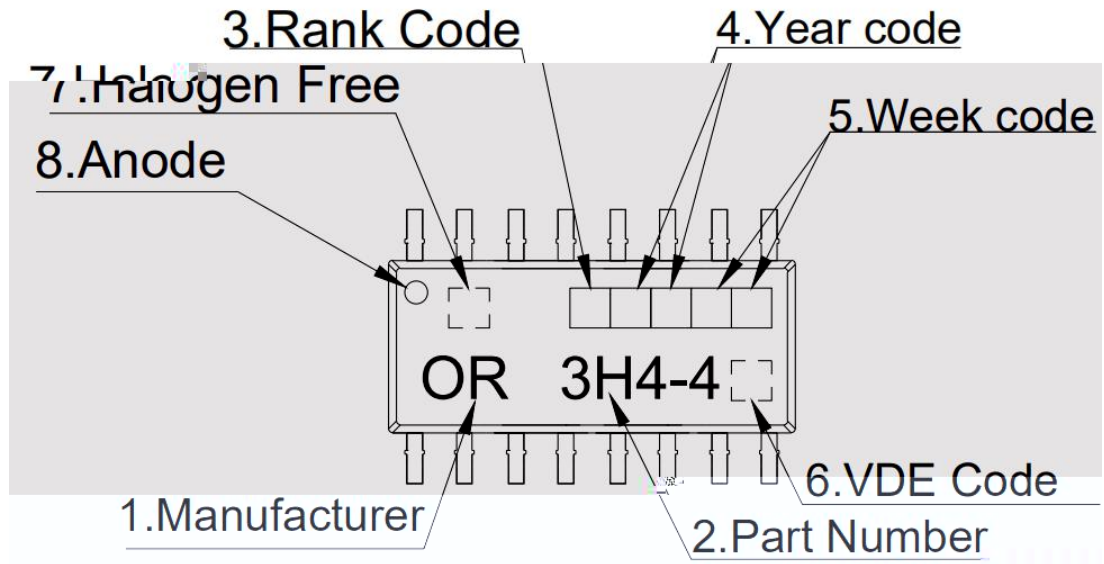
- Current Conversion Ratio =  $I_C / I_F \times 100\%$

## 7. Order Information

Part Number

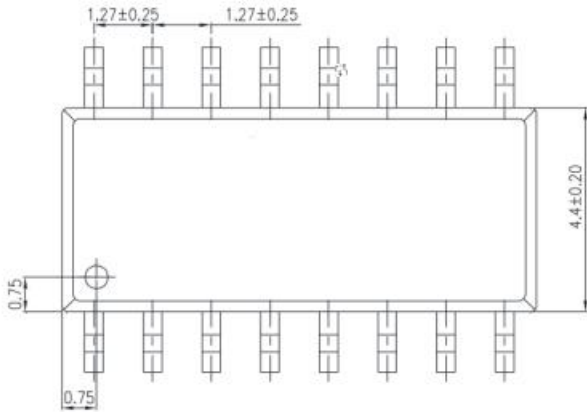
**OR-3**

## 8. Naming Rule

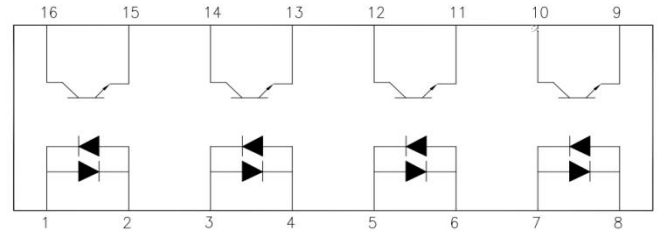


\*  
\*

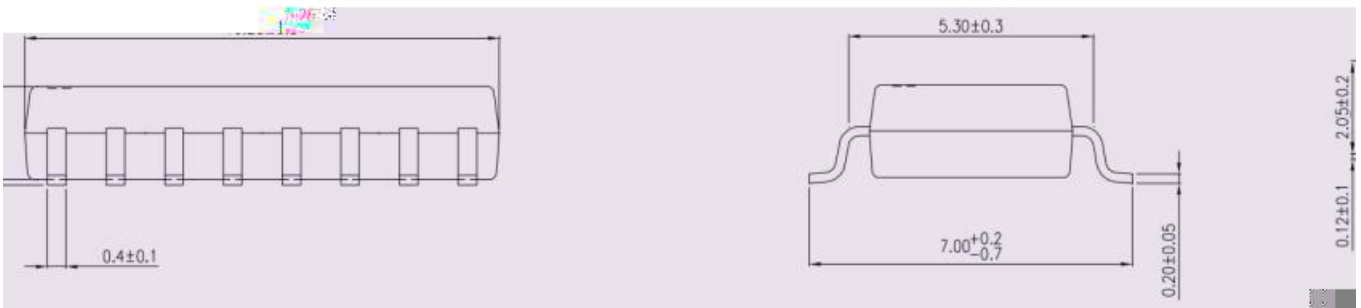
### 9. Outer Dimension



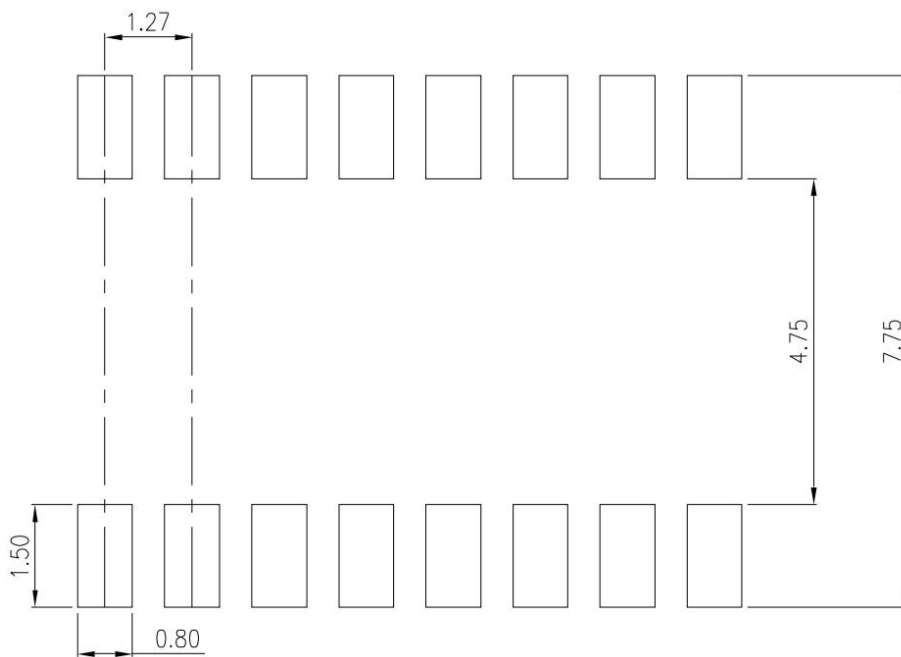
PIN NO. AND INTERNAL CONNECTION DIAGRAM



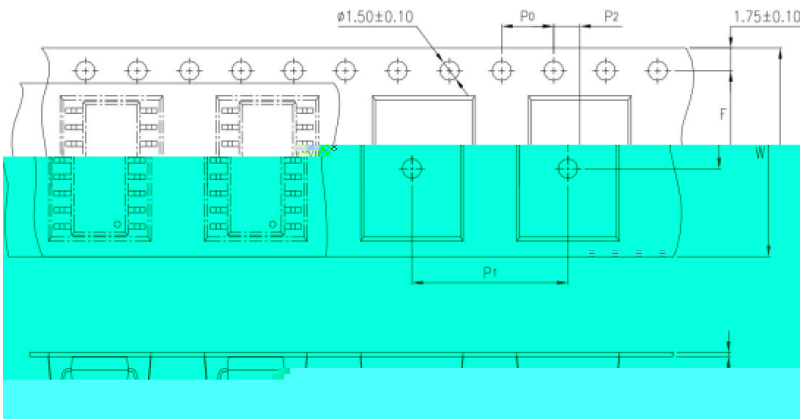
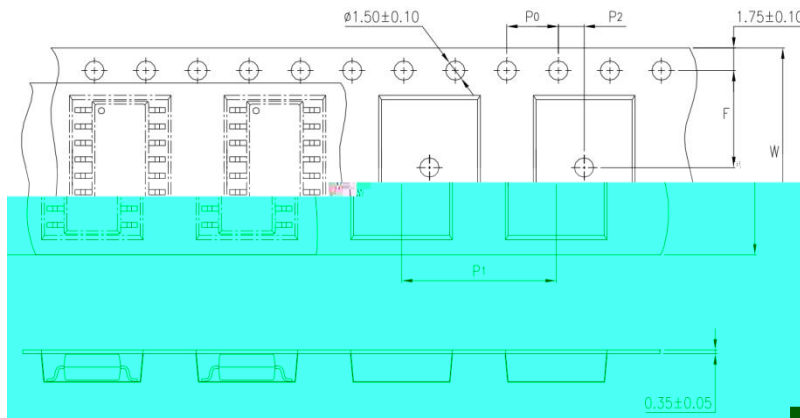
1,3,5,7. Anode,Cathode      9,11,13,15. Emitter  
 2,4,6,8. Cathode,Anode    10,12,14,16. Collector



### 10. Recommended Foot Print Patterns (Mount Pad) (Unit:mm)



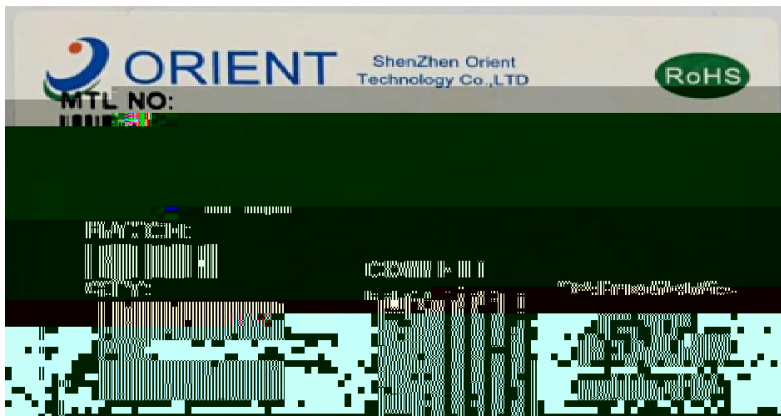
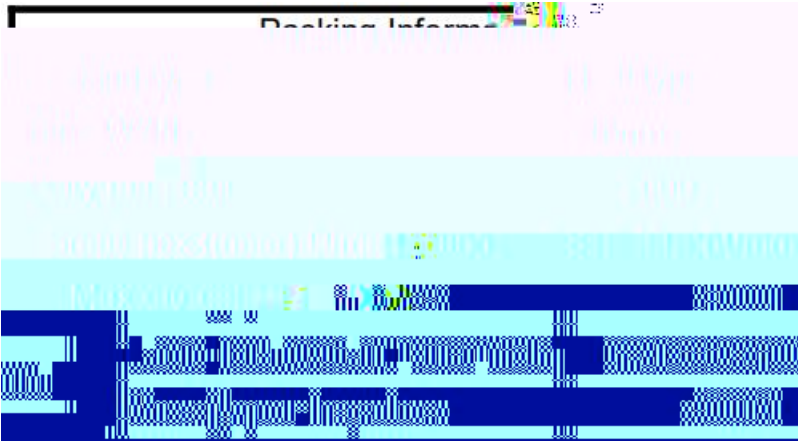
## 11. Taping Dimensions



type	Symbol	Dimensions: mm (in.)
bandwidth h	W	16±0.3 (0.47)
pitch	P0	4±0.1 (0.15)
pitch	F	7.5±0.1 (0.217)
	P2	2±0.1 (0.079)
interval	P1	12±0.1 (0.315)

Encapsulation type	TA1/TA
Quantity (pieces)	2000

## 12. Package Dimension



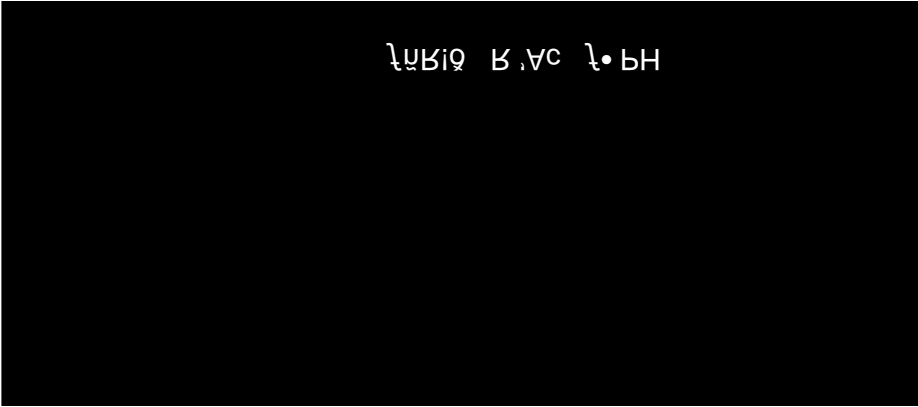
1. MTL NO:Contents with "Order Information" in the specification.
2. LOT NO:The production cycle of the product.
3. BATCH:The CTR RANK of the product.
4. Quantity:Product packaging quantity.
5. Product Data: The data when product be made.



### 13. Reliability Test



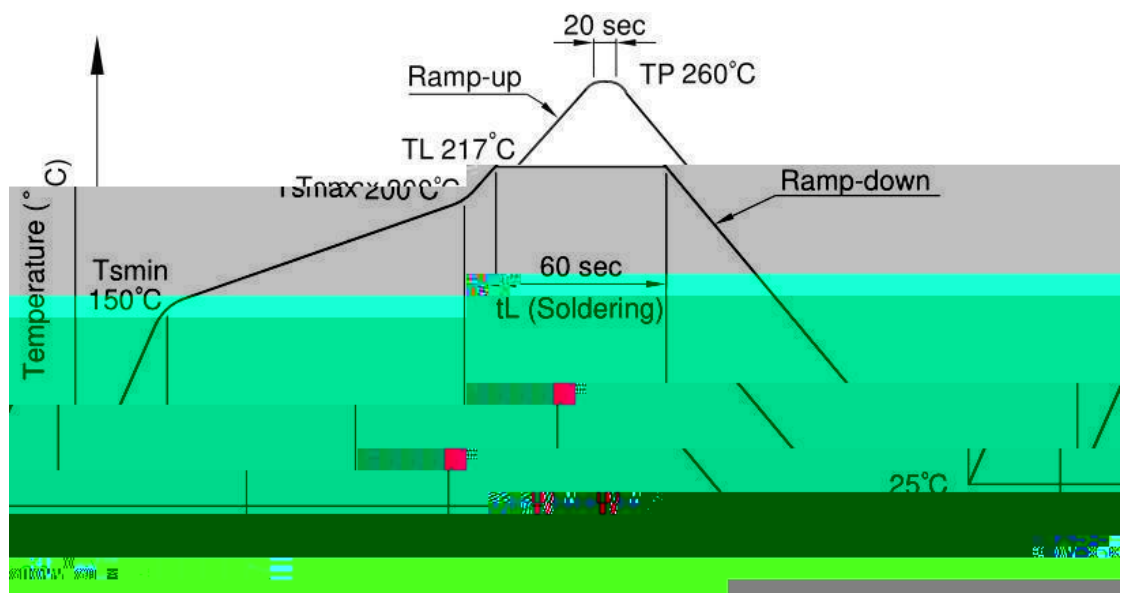
NO.	ITEMS	QTY. (Pcs)	Condition	Standard
1	RSH	260	5	JESD22-A106
2	HTSL	125		JESD22-A103
3	LTSL	-55		JESD22-A119
4	TC		H:125 15min 5min L:-55 15min H:000 5min	JESD22-A104
5S	TS	7	15s L:-40 5min	JESD22-A106



### 14. Temperature Profile Of Soldering

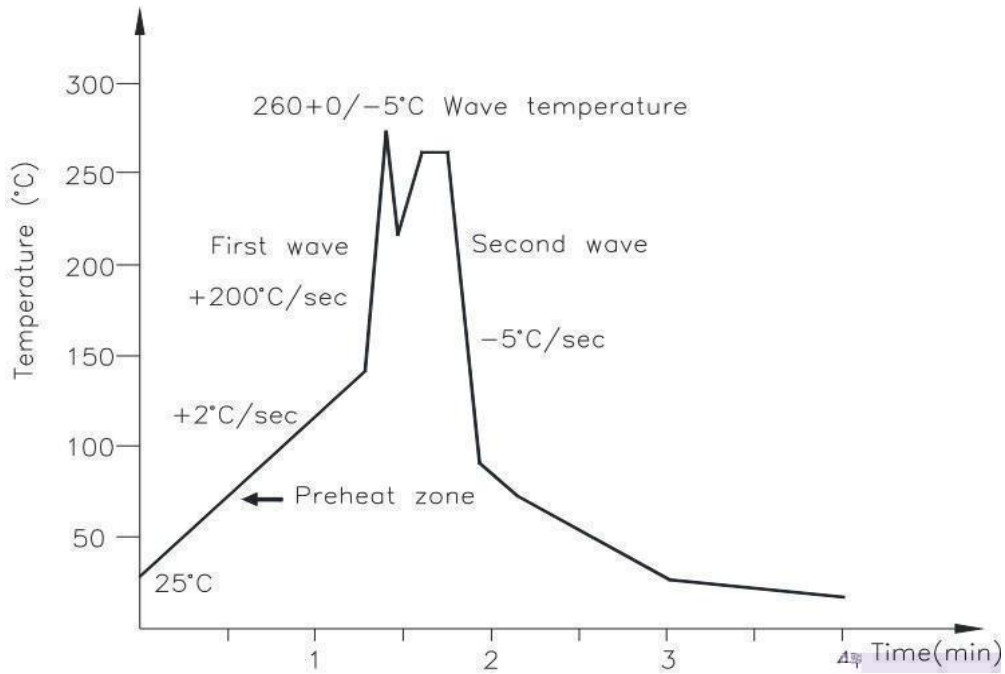
#### 1 IR Reflow soldering (JEDEC-STD-020C compliant)

Profile item	Conditions
- ( )	
- ( )	
- ( ) ( )	
- ( )	
- ( )	



**2 Wave soldering (JEDEC22A111 compliant)**

	+   -



**3 Hand soldering by soldering iron**

Temperature	380+0/-5°C
Time	3 sec max

### 15. Characteristics Curve

Figure 1. Collector Power Dissipation vs. Ambient Temperature

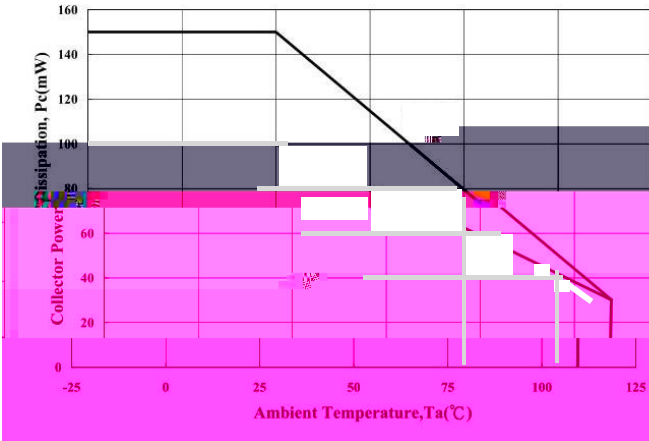


Figure 2. Forward Current vs. Ambient Temperature

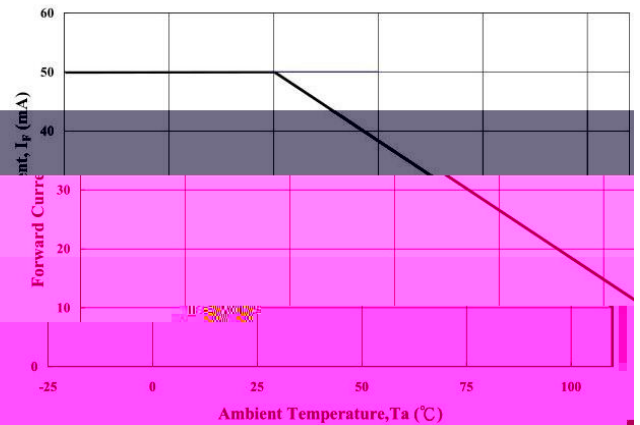


Figure 3. Forward Current vs. Forward Voltage



Figure 4. Forward Voltage Temperature Coefficient vs. Forward Current



Figure 5. Pulse Forward Current vs. Duty Cycle Ratio

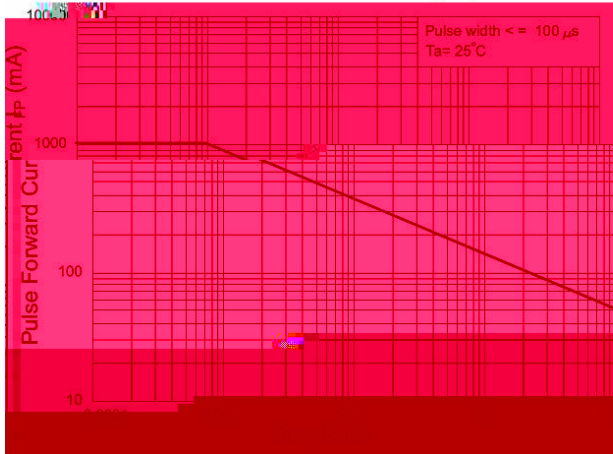


Figure 6. Pulse Forward Current vs. Pulse Forward

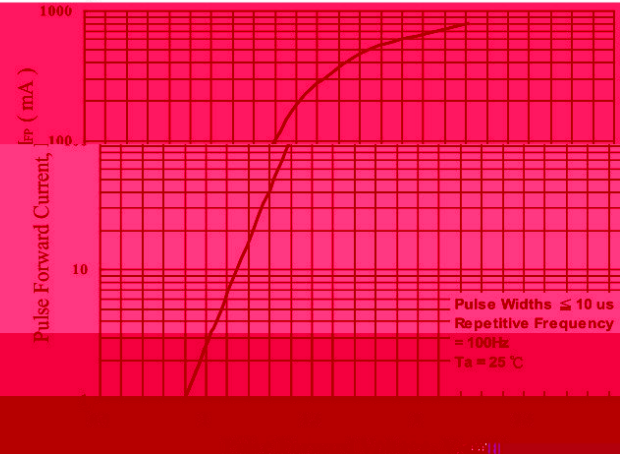


Figure 7. Collector-Emitter Saturation Voltage vs. Forward

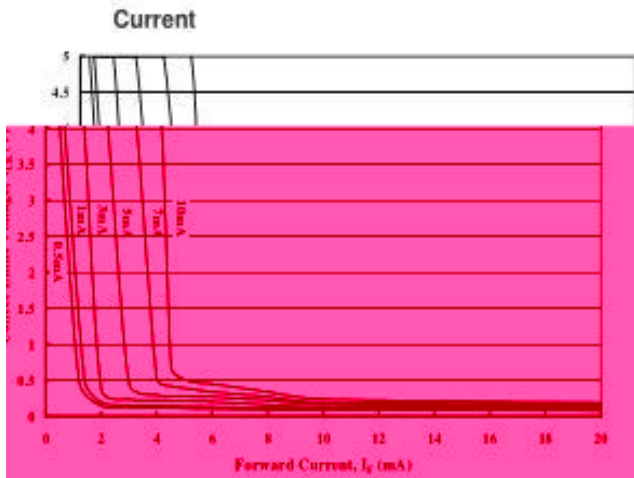


Figure 8. Collector Current vs. Collector-Emitter

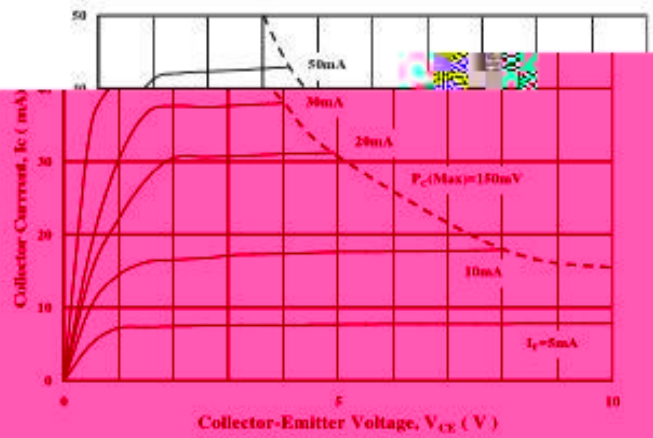


Figure 9. Collector Current vs. Small Collector-Emitter

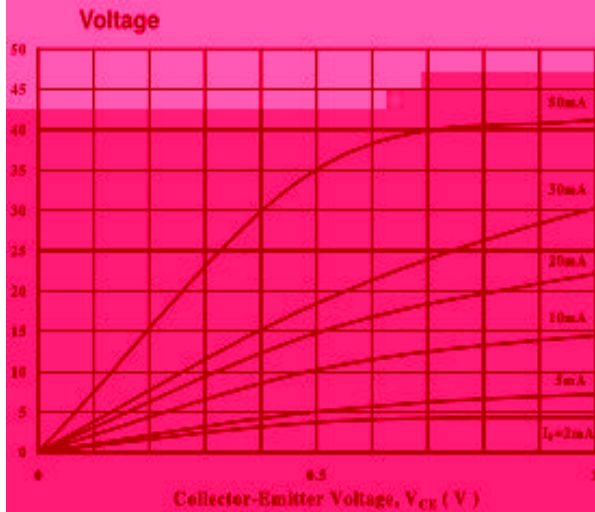


Figure 10. Normalized CTR vs. Forward

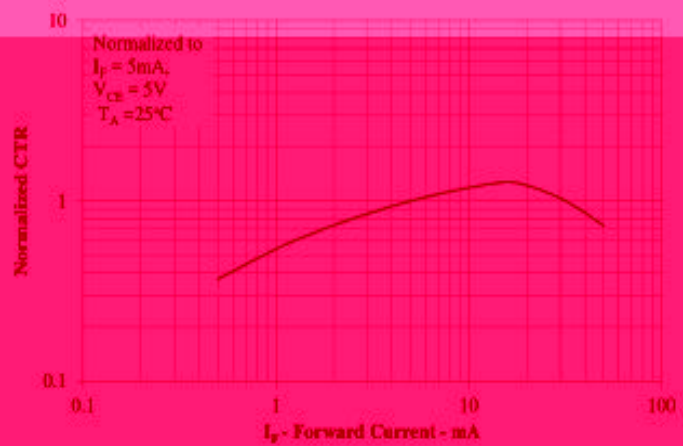


Figure 11. Collector Dark Current vs. Ambient Temperature

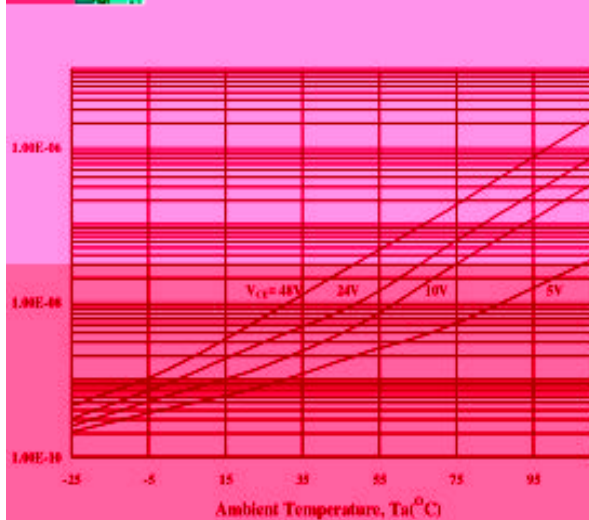


Figure 12. Current Transfer Ratio vs. Forward

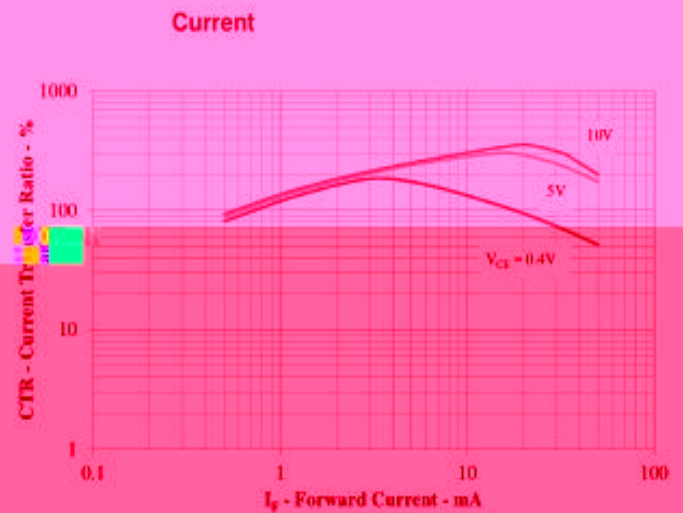


Figure 13. Normalized CTR vs. Ambient Temperature

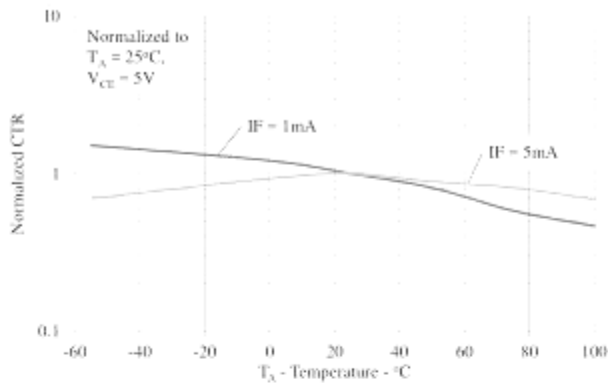


Figure 14. Collector-Emitter Saturation Voltage vs. Ambient Temperature

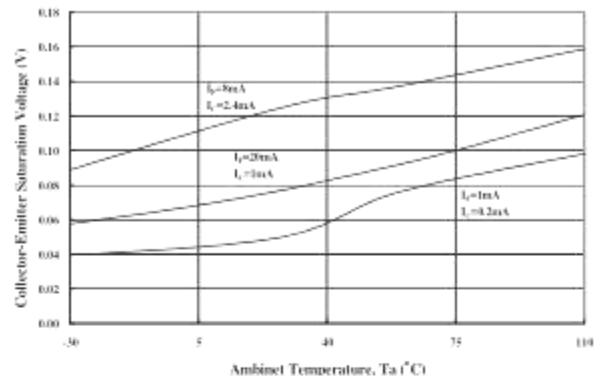


Figure 15. Collector Current vs. Ambient Temperature

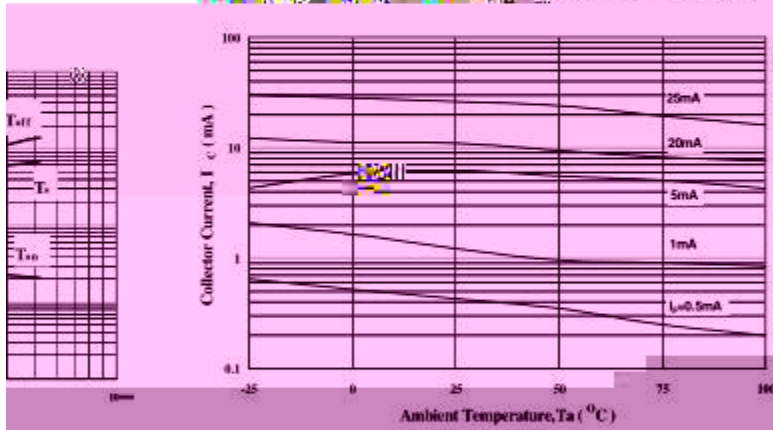


Figure 16. Switching Time vs. Load Resistance

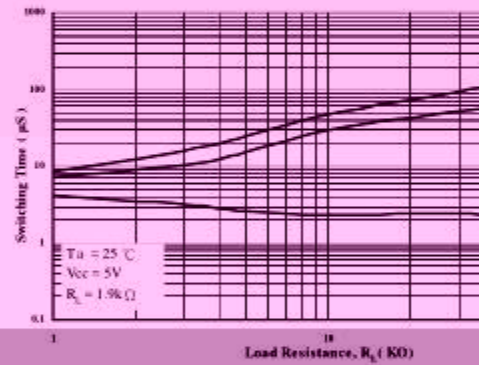


Figure 17. Switching Time vs. Ambient Temperature

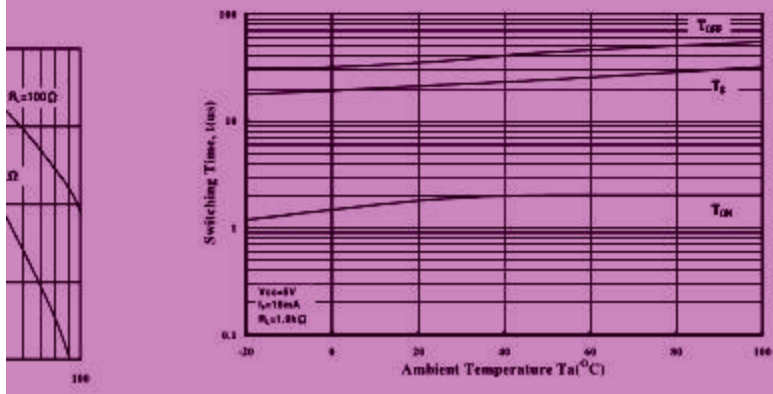


Figure 18. Frequency Response

